

09-30-2003

FORM PTO-1595  
(Rev. 10/02)

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U.S. DEPARTMENT OF COMMERCE  
Patent and Trademark Office

Docket No.: 67162-021

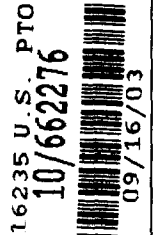
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To the Honorable Commissioner for Patents and Trademarks: Please record the attached original documents or copy thereto:

1. Name of Conveying Party(ies):  
Ryu MAKABE, Yuichi KUNORI  
Additional name(s) of conveying party(ies) attached?  Yes  No

9-16-03

2. Name and address of receiving party(ies):  
Name: RENESAS TECHNOLOGY CORP.  
Address: 4-1, Marunouchi 2-chome,  
Chiyoda-ku,  
TOKYO 100-6334 JAPAN



3. Nature of Conveyance:  
 Assignment  Merger  
 Security Agreement  Change of Name  
 Other

Execution Date: August 1, August 1, 2003

Additional name(s) & address(es) attached?  Yes  No

4. Application number(s) or patent number(s):  
If the document is being filed together with a new application, the execution date of the application is: August 1, August 1, 2003

A. Patent Application No(s).

B. Patent No(s).

10662276

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: MCDERMOTT, WILL & EMERY  
Internal Address:

Street Address: 600 13th Street, N.W.

City: Washington State: D. C. Zip: 20005-3096

6. Total number of applications and patents involved:

7. Total fee (37 CFR 3.41) \$40.00

Enclosed

Authorized to be charged to deposit account

8. Deposit account number:

500417

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Stephen A. Becker, 26,527

September 16, 2003

Name and Registration No. of Person Signing

Signature

Date

Total number of pages including cover sheet: 3

OMB No. 0651-0027 (exp. 6/30/2005)

09/25/2003 ECOMPER 00000192 500417 10662276

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PATENT  
REEL: 014534 FRAME: 0674

Attorney Docket No.: \_\_\_\_\_

**ASSIGNMENT**

WHEREAS, Ryu MAKABE and Yuichi KUNORI,  
hereinafter called the "Assignor," has invented a new and useful invention entitled  
SEMICONDUCTOR WAFER, SEMICONDUCTOR CHIP AND DICING METHOD OF A SEMICONDUCTOR  
WAFER  
\_\_\_\_\_, for which he has:

- (a) filed an application for United States Letters Patent on \_\_\_\_\_ as (Serial No. \_\_\_\_\_); or
- (b) executed an application for United States Letters Patent on August 1, 2003 \_\_\_\_\_; or
- (c) filed a provisional application on \_\_\_\_\_ as (Serial No. \_\_\_\_\_); and

WHEREAS, Renesas Technology Corp., a corporation organized and existing under the laws of Japan, having a place of business at: 4-1, Marunouchi 2-chome, Chiyoda-ku, TOKYO 100-6334 JAPAN

hereinafter called the "Assignee," is desirous of acquiring the entire right, title and interest in and to said invention, the application above identified, and in, to and under any Letters Patent which may be obtained to said invention, as hereinafter more fully set forth;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for and in consideration of the sum of One Dollar (\$1.00), and other valuable and legally sufficient considerations, the receipt of which by said Assignor from the said Assignee is hereby acknowledged, the said Assignor has sold, assigned and transferred, and by these presents do sell, assign and transfer unto the said Assignee, the entire, right, title and interest for the United States in and to the invention and application hereinabove identified, and any Letters Patent of the United States that may issue for said invention, together with the entire right, title and interest in and to said invention and applications for Letters Patent and Letters Patent therefor, in all countries foreign to the United States, including the full right to claim for any such application all benefits and priority rights under any applicable convention; to have and to hold for the sole and exclusive use and benefit of the said Assignee, its successors and assigns, to the full end of the term or terms for which any and all of said Letters Patent for said inventions may issue.

And the said Assignor does hereby covenant and agree, for himself and his legal representatives, that he will assist the said Assignee in the prosecution of the application herein identified; in the making and prosecution of any other applications for Letters Patent that the said Assignee may elect to make covering the invention herein identified, as hereinabove set forth; in vesting in the said Assignee like exclusive title in and to all such other applications and Letters Patent; and in the prosecution of any interference which may arise involving said invention, or any application or Letters Patent herein contemplated; and that they will execute and deliver to the said Assignee any and all additional papers which may be requested by the said Assignee to fully carry out the terms of this Assignment.

The undersigned hereby grant(s) the attorneys of McDermott, Will & Emery the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

And the Commissioner of Patents and Trademarks is hereby authorized and requested to issue Letters Patent to the said Assignee in accordance with the terms of this Assignment.

IN TESTIMONY WHEREOF, the said Assignor has hereunto set his hands and affixed his seal.

Date: August 1, 2003  
(Seal)

Ryo Mchabe

Date: August 1, 2003  
(Seal)

Yuichi Kumori

Date: \_\_\_\_\_  
(Seal)

\_\_\_\_\_

Date: \_\_\_\_\_  
(Seal)

\_\_\_\_\_

Date: \_\_\_\_\_  
(Seal)

\_\_\_\_\_

Date: \_\_\_\_\_  
(Seal)

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